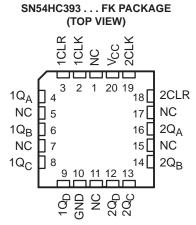
SCLS143D - DECEMBER 1982 - REVISED JULY 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 13 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Dual 4-Bit Binary Counters With Individual Clocks
- Direct Clear for Each 4-Bit Counter
- Can Significantly Improve System Densities by Reducing Counter Package Count by 50 Percent

description/ordering information

The 'HC393 devices contain eight flip-flops and additional gating to implement two individual 4-bit counters in a single package. These devices comprise two independent 4-bit binary counters, each having a clear (CLR) and a clock (CLK) input. N-bit binary counters can be implemented with each package, providing the capability of divide by 256. The 'HC393 devices have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system timing signals.

SN54H0	2393	J OR V	V PACK	AGE
SN74HC393	. D, DB	, N, NS,	OR PW	PACKAGE
	(TO	P VIEW)	



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HC393N	SN74HC393N
		Tube of 50	SN74HC393D	
	SOIC – D	Reel of 2500	SN74HC393DR	HC393
		Reel of 250	SN74HC393DT	
–40°C to 85°C	SOP – NS	Reel of 2000	SN74HC393NSR	HC393
	SSOP – DB	Reel of 2000	SN74HC393DBR	HC393
		Tube of 90	SN74HC393PW	
	TSSOP – PW	Reel of 2000	SN74HC393PWR	HC393
		Reel of 250	SN74HC393PWT	
	CDIP – J	Tube of 25	SNJ54HC393J	SNJ54HC393J
–55°C to 125°C	CFP – W Tube of 150		SNJ54HC393W	SNJ54HC393W
	LCCC – FK Tube of 55		SNJ54HC393FK	SNJ54HC393FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

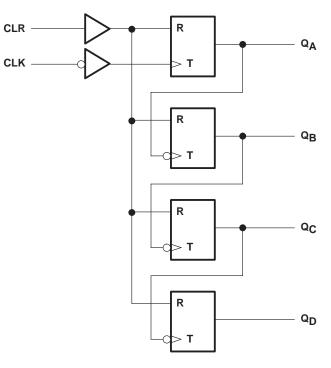


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FUNCTION TABLE COUNT SEQUENCE (each counter)								
COUNT		OUT	PUTS					
COUNT	QD	QC	QB	QA				
0	L	L	L	L				
1	L	L	L	н				
2	L	L	Н	L				
3	L	L	Н	н				
4	L	Н	L	L				
5	L	Н	L	н				
6	L	Н	Н	L				
7	L	Н	Н	н				
8	н	L	L	L				
9	н	L	L	н				
10	н	L	Н	L				
11	н	L	Н	н				
12	н	Н	L	L				
13	н	Н	L	н				
14	н	Н	Н	L				
15	н	Н	Н	Н				

logic diagram, each counter (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

1 1 1	 Note 1) (see Note 1) D package DB package N package NS package PW package 	±20 mA ±20 mA ±25 mA ±50 mA 86°C/W 96°C/W 80°C/W 76°C/W 76°C/W
Storage temperature range, T _{stg}		5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	154HC39	93	SN	174HC39)3	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
	Ī	V _{CC} = 6 V	4.2			4.2			
		$V_{CC} = 2 V$			0.5			0.5	V
VIL	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	
		V _{CC} = 6 V			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$			1000			1000	
$\Delta t/\Delta v^{\dagger}$	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
ТА	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

[†] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		Vaa	T _A = 25°C			SN54HC393		SN74HC393		UNIT
PARAMETER	TEST CC	INDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
		I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
	VI = VIH or VIL		2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL			6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
l	$V_{I} = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_{I} = V_{CC} \text{ or } 0,$	I _O = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			Vee	T _A = 2	25°C	SN54H	C393	SN74H	C393	UNIT
			Vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		28	
			2 V	80		120		100		
		CLK high or low	4.5 V	16		24		20		ns
.	Pulse duration		6 V	14		20		18		
tw	Fuise duration		2 V	80		120		100		
		CLR high	4.5 V	16		24		20		
			6 V	14		20		18		
			2 V	25		25		25		
t _{su}	Setup time, CLR inactive		4.5 V	5		5		5		ns
			6 V	5		5		5		



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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

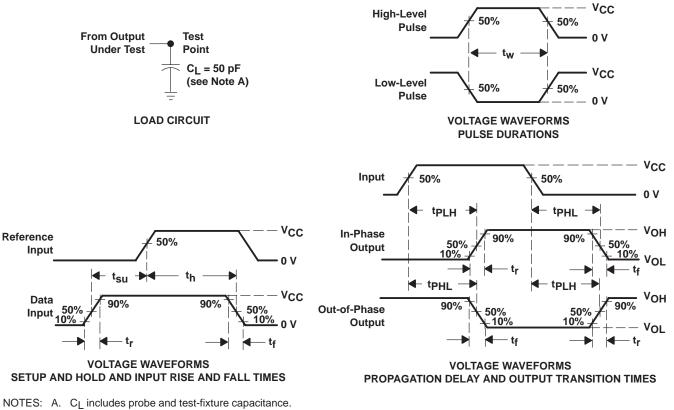
PARAMETER	FROM	то	Nee	Т	ς = 25°C	;	SN54F	IC393	SN74HC393		UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		Q _A	2 V	6	10		4.2		5		
fmax	CLK		4.5 V	31	50		21		25		MHz
			6 V	36	60		25		28		
			2 V		50	120		180		150	
		QA	4.5 V		15	24		36		30	
			6 V		13	20		31		26	
	CLK	QB	2 V		72	190		285		240	
			4.5 V		22	38		57		47	ns
÷.			6 V		18	32		48		40	
^t pd	ULK	QC	2 V		91	240		360		300	
			4.5 V		28	48		72		60	
			6 V		22	41		61		51	
			2 V		100	290		430		360	
		QD	4.5 V		32	58		87		72	
			6 V		24	50		74		62	
			2 V		45	165		250		205	
^t PHL	CLR	Any	4.5 V		17	33		49		41	ns
			6 V		14	28		42		35	
			2 V		28	75		110		95	
tt		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per counter	No load	40	pF



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PARAMETER MEASUREMENT INFORMATION

- - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 6 ns, t_f = 6 ns.
 - C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



TEXAS INSTRUMENTS www.ti.com

14-Nov-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84100012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8410001CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
8410001DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/66309BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54HC393J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74HC393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393DTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC393N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74HC393NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393PWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC393PWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC393FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC393J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC393W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

PACKAGE OPTION ADDENDUM



LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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